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REMARKS

The Applicants reconsideration of the rejection.

Claims 11-17, and 19-31 are now pending. Please cancel Claim 18 without prejudice or disclaimer.

Claims 1-3, and 5 were rejected under 35 U.S.C. §102(b) as being anticipated by Otremba et al., U.S. 4,922,211 (Otremba). This rejection is moot in view of the cancellation of Claims 1-10.

Claims 4, 6, and 12-16 were rejected under 35 U.S.C. §103(a) as being unpatentable over Otremba. Claims 7-11 and 16-19 were rejected under 35 U.S.C. §103(a) as being unpatentable over Cachier, U.S. 4,054,875 (Cachier) in view of Otremba. Claims 20-27 were rejected under 35 U.S.C. §103(a) as being unpatentable over Otremba in view of Cachier. The rejections of claims 4 and 6-10 are moot in view of the cancellation of these claims. The rejections of the other claims are respectfully traversed as follows.

As set forth in the amended independent Claim 11 and its dependent claims, the inventive transceiver apparatus includes an RF oscillator apparatus having a cavity resonator and a conductor plate which supports a microwave monolithic integrated circuit chip electromagnetically coupled to the cavity resonator. An advantageous feature of this structure

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is that the transceiver can be modularized, contributing to a reduction in size of the transceiver apparatus in accordance with the reduced size of the RF oscillator apparatus. Neither Otremba nor Cachier suggests a construction which brings such an advantage.

Independent Claim 20 is directed to a manufacturing process of a transceiver apparatus, including a step of preparing a RF oscillator apparatus, a first semiconductor chip constituting a receiving section, and a second semiconductor chip constituting a transmitting section; a step of fixing the RF oscillator apparatus and the first and second semiconductor chips to a module substrate by an adhesive; and a step of airtightly sealing the RF oscillator apparatus and the first and second semiconductor chips loaded on the module substrate. Thus, in Claim 20, the modularization of the transceiver apparatus is positively claimed. Further, the entirety of the RF oscillator apparatus and first and second semiconductor chips are airtightly sealed.

Otremba discloses a structure in which an oscillator circuit is disposed outside an airtight seal. See Figure 1 of the patent (active oscillator 5 is disposed on the lower side of printed board 4, outside the sealed dielectric resonator 8). Further, Cachier discloses a structure in which the oscillation element (diode) is coupled by disposing a

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dielectric block so as to surround the oscillation element. Cachier's dielectric resonator both determines the frequency of the oscillator and also acts a radiating antenna. Therefore, Cachier is not properly combinable with Otremba, and is substantially different from both Otremba and the present invention.

Thus, both Otremba and Cachier fail to suggest or teach the technical idea and effect of reducing the size of the oscillator assembly by modularization and optionally airtight sealing.

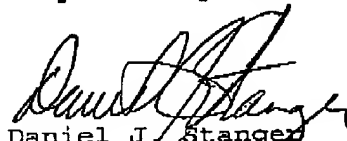
Claims 1-27 were also provisionally rejected under 35 U.S.C. §101 as claiming the same invention as that of Claims 1-27 of co-pending application number 09/810,400. However, the formerly co-pending application has been abandoned, rendering moot the double-patenting rejection.

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In view of the foregoing amendments and remarks, the Applicants respectfully request reconsideration of the application and allowance of the claims.

Respectfully submitted,



Daniel J. Stanger
Registration No. 32,846
Attorney for Applicants

MATTINGLY, STANGER & MALUR, P.C.
1800 Diagonal Road, Suite 370
Alexandria, Virginia 22314
Telephone: (703) 684-1120
Facsimile: (703) 684-1157
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